

Data Sheet January 2002

# 30A, 400V - 600V Hyperfast Diodes

The RHRG3040 and RHRG3060 are hyperfast diodes with soft recovery characteristics ( $t_{rr}$  < 40ns). They have half the recovery time of ultrafast diodes and are of silicon nitride passivated ion-implanted epitaxial planar construction.

These devices are intended for use as freewheeling/ clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

Formerly developmental type TA49063.

# Ordering Information

PART NUMBER	PACKAGE	BRAND
RHRG3040	TO-247	RHRG3040
RHRG3060	TO-247	RHRG3060

NOTE: When ordering, use the entire part number.

# Symbol



### **Features**

•	Hyperfast with Soft Recovery<40ns	3
•	Operating Temperature175°C	;
•	Reverse Voltage Up To	/

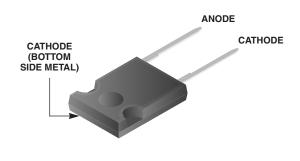
- Avalanche Energy Rated
- · Planar Construction

# **Applications**

- · Switching Power Supplies
- Power Switching Circuits
- · General Purpose

### **Packaging**

**JEDEC STYLE TO-247** 



-65 to 175

#### Absolute Maximum Ratings T<sub>C</sub> = 25°C, Unless Otherwise Specified **RHRG3040 RHRG3060** UNITS Peak Repetitive Reverse Voltage ...... VRRM 400 600 400 600 400 600 V 30 30 $(T_C = 120^{\circ}C)$ 70 70 (Square Wave, 20kHz) 325 325 (Halfwave, 1 Phase, 60Hz) 125 125 W 20 20 m.J

-65 to 175

οС

### RHRG3040, RHRG3060

### **Electrical Specifications** $T_C = 25^{\circ}C$ , Unless Otherwise Specified

		RHRG3040		RHRG3060				
SYMBOL	TEST CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
V <sub>F</sub>	I <sub>F</sub> = 30A	-	-	2.1	-	-	2.1	V
	$I_F = 30A, T_C = 150^{\circ}C$	-	-	1.7	-	-	1.7	V
I <sub>R</sub>	V <sub>R</sub> = 400V	-	-	250	-	-	-	μА
	V <sub>R</sub> = 600V	-	-	-	-	-	250	μА
	V <sub>R</sub> = 400V, T <sub>C</sub> = 150°C	-	-	1.0	-	-	-	mA
	V <sub>R</sub> = 600V, T <sub>C</sub> = 150°C	-	-	-	-	-	1.0	mA
t <sub>rr</sub>	I <sub>F</sub> = 1A, dI <sub>F</sub> /dt = 200A/μs	-	-	40	-	-	40	ns
	$I_F = 30A$ , $dI_F/dt = 200A/\mu s$	-	-	45	-	-	45	ns
ta	I <sub>F</sub> = 30A, dI <sub>F</sub> /dt = 200A/μs	-	22	-	-	22	-	ns
t <sub>b</sub>	$I_F = 30A$ , $dI_F/dt = 200A/\mu s$	-	18	-	-	18	-	ns
Q <sub>RR</sub>	$I_F = 30A$ , $dI_F/dt = 200A/\mu s$	-	100	-	-	100	-	nC
СЈ	V <sub>R</sub> = 10V, I <sub>F</sub> = 0A	-	85	-	-	85	-	pF
$R_{ heta JC}$		-	-	1.2	-	-	1.2	°C/W

### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

 $I_R$  = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (See Figure 9), summation of  $t_a$  +  $t_b$ .

ta = Time to reach peak reverse current (See Figure 9).

 $t_b$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

 $Q_{RR}$  = Reverse recovery charge.

 $C_J$  = Junction Capacitance.

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = Pulse width.

D = Duty cycle.

### **Typical Performance Curves**

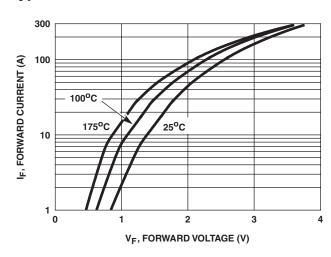


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

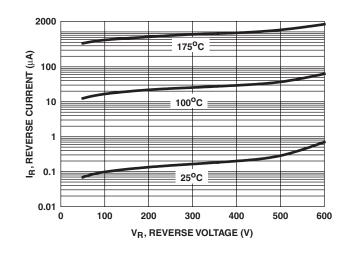


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

# Typical Performance Curves (Continued)

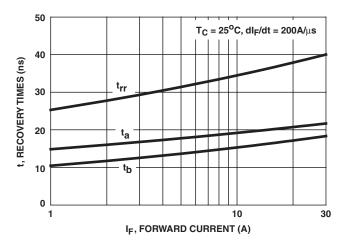


FIGURE 3.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

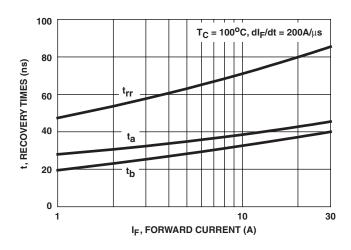


FIGURE 4.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

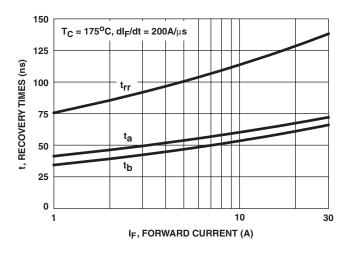


FIGURE 5.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

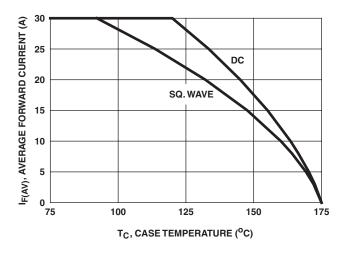


FIGURE 6. CURRENT DERATING CURVE

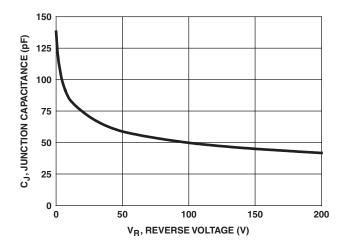


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

©2002 Fairchild Semiconductor Corporation RHRG3040, RHRG3060 Rev. B

### Test Circuits and Waveforms

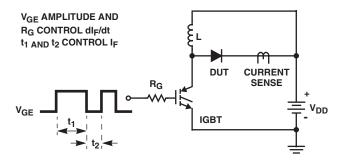


FIGURE 8. t<sub>rr</sub> TEST CIRCUIT

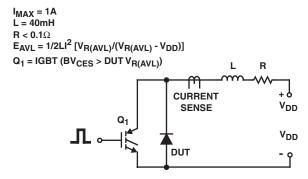


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

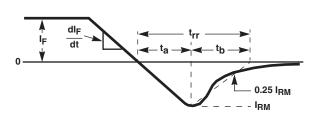


FIGURE 9. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

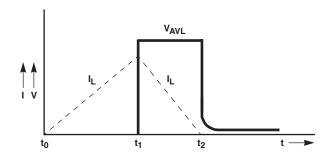


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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